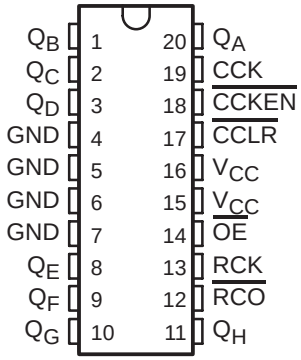
- **Inputs Are TTL-Voltage Compatible**
- **Parallel Registered Outputs**
- **Internal Counters Have Direct Clear**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Package Options Include Plastic Small-Outline Packages and Standard Plastic 300-mil DIPs**

DW OR N PACKAGE
(TOP VIEW)



description

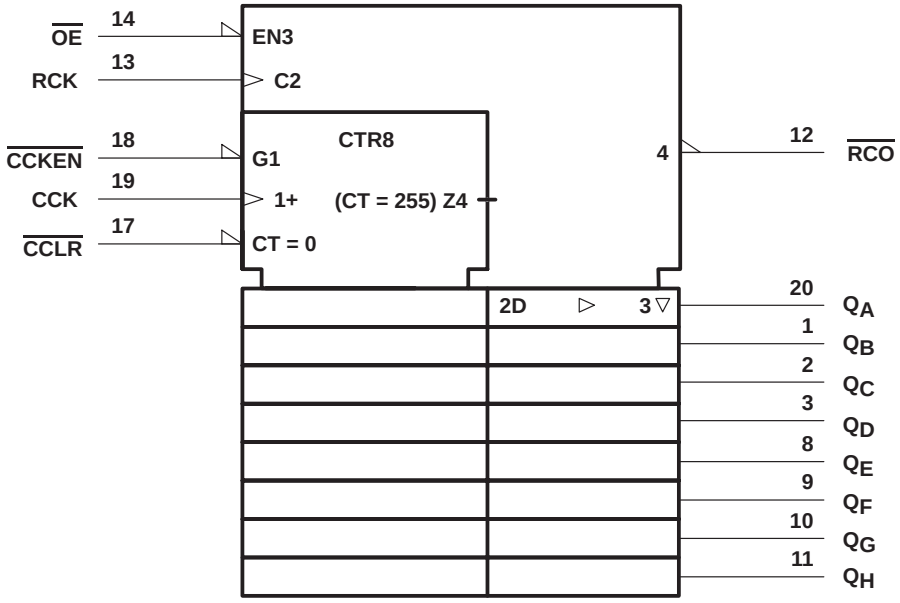
The 74ACT11590 contains an 8-bit binary counter that feeds an 8-bit storage register. The storage register has parallel outputs. Separate clocks are provided for both the binary counter and storage register.

The binary counter features a direct clear ($\overline{CCLR}$) input and a count-enable ($\overline{CCKEN}$) input. For cascading, a ripple-carry ($\overline{RCO}$) output is provided. Expansion is easily accomplished for two stages by connecting $\overline{RCO}$ of the first stage to $\overline{CCKEN}$ of the second stage. Cascading for larger count chains can be accomplished by connecting $\overline{RCO}$ of each stage to CCK of the following stage.

Both the register and the counter have individual positive-edge-triggered clocks. If both clocks are connected together, the counter state is always one count ahead of the register. Internal circuitry prevents clocking from the clock enable.

The 74ACT11590 is characterized for operation from −40°C to 85°C.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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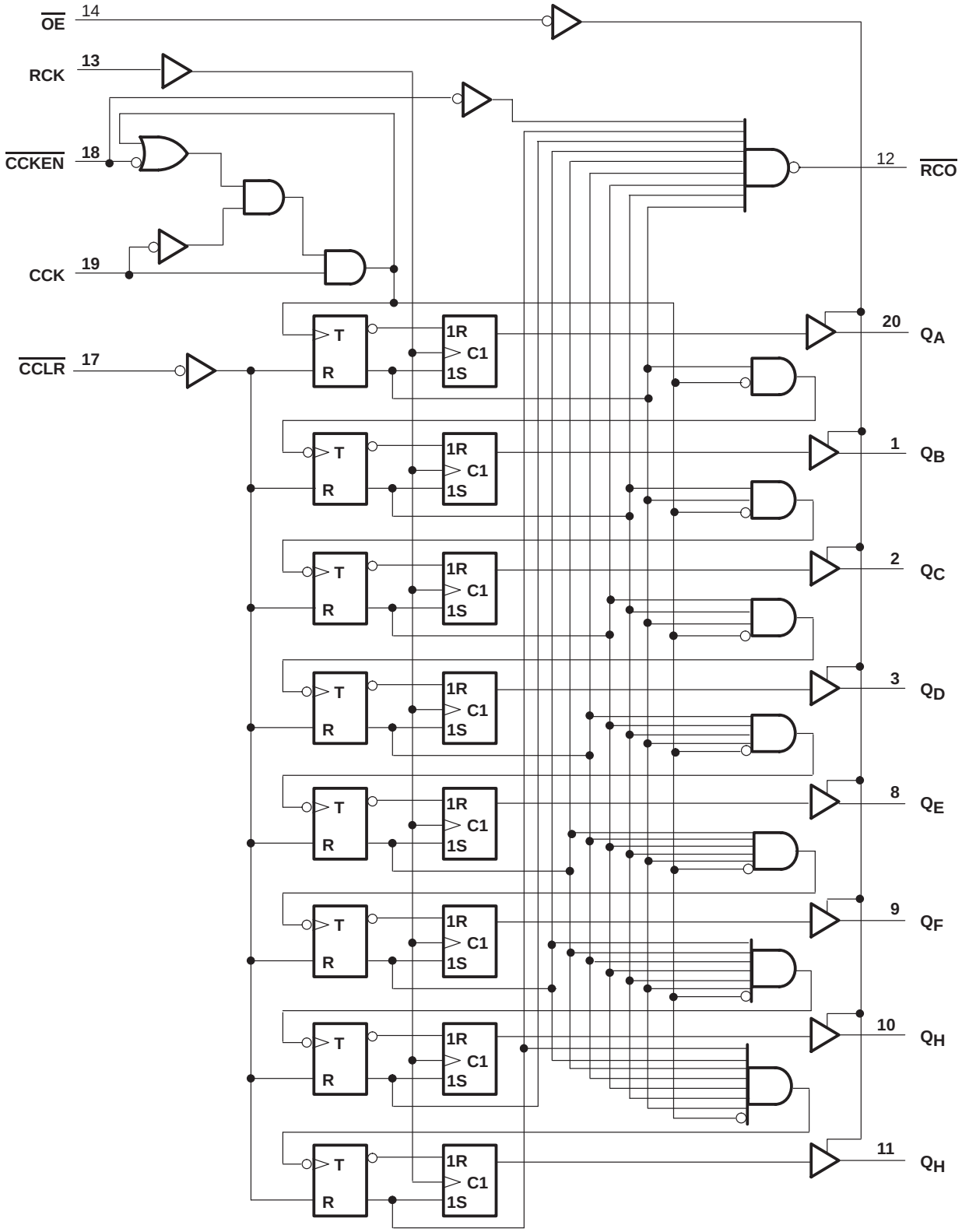
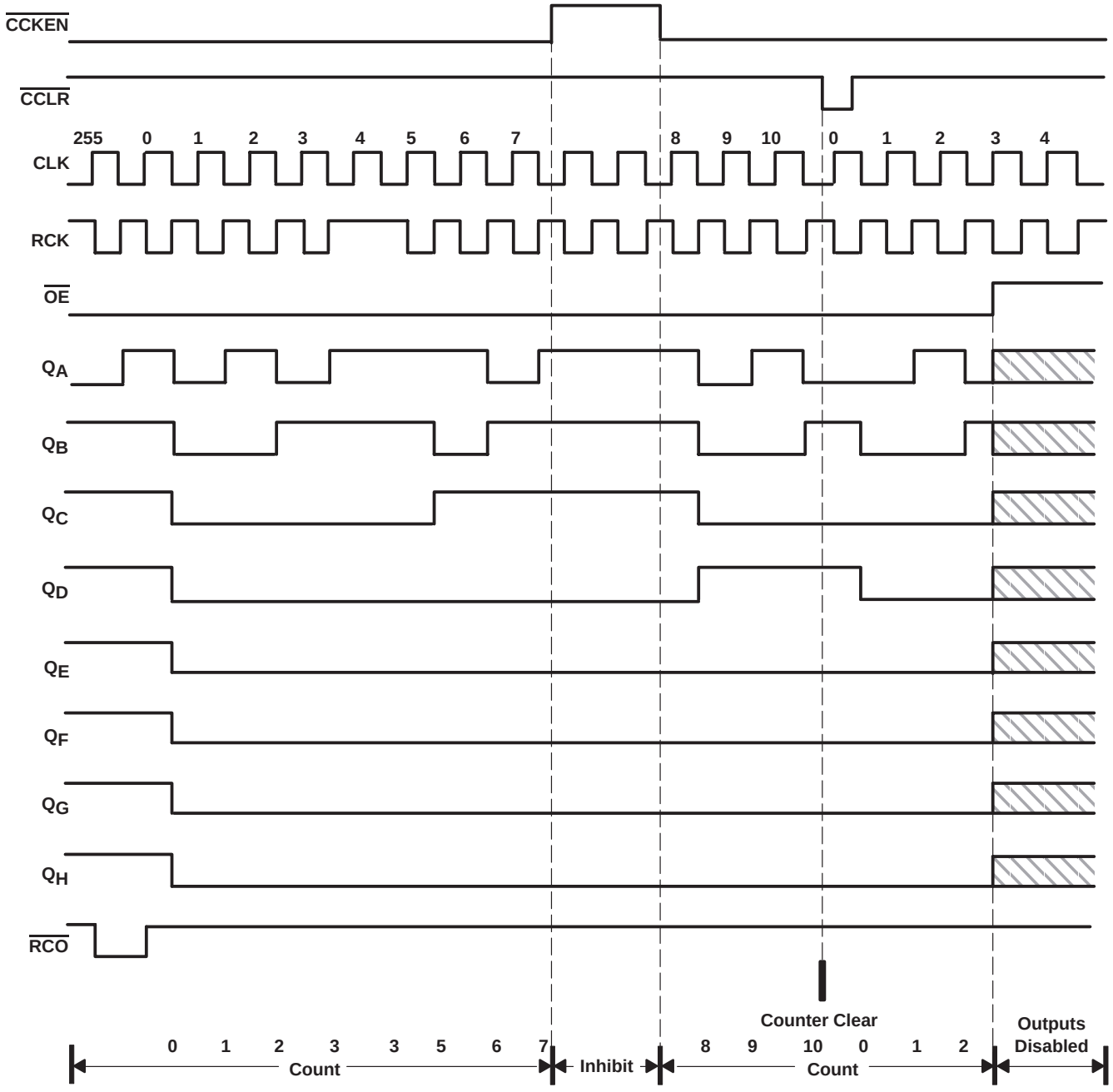
logic diagram (positive logic)



typical operating sequence



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . −0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . . −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) . . . . . −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) . . . . . ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) . . . . . ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) . . . . . ±50 mA
Continuous current through V_{CC} or GND . . . . . ±225 mA
Storage temperature range . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
I_{OH}	High-level output current			−24	mA
I_{OL}	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
T_A	Operating free-air temperature	−40		85	°C

NOTE 2: Unused or floating inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V_{OH}	I_{OH} = −50 µA	4.5 V	4.4			4.4		V
		5.5 V	5.4			5.4		
	I_{OH} = −24 mA	4.5 V	3.94			3.8		
		5.5 V	4.94			4.8		
	I_{OH} = −75 mA†	5.5 V				3.85		
V_{OL}	I_{OL} = 50 µA	4.5 V			0.1		0.1	V
		5.5 V			0.1		0.1	
	I_{OL} = 24 mA	4.5 V			0.36		0.44	
		5.5 V			0.36		0.44	
	I_{OL} = 75 mA†	5.5 V					1.65	
I_I	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	µA
I_{OZ}	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	µA
I_{CC}	$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		80	µA
ΔI_{CC}‡	One input at 3.4 V, Other inputs at V_{CC} or GND	5.5 V			0.9		1	mA
C_i	$V_I = V_{CC}$ or GND	5 V		3				pF
C_o	$V_O = V_{CC}$ or GND	5 V		11				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		MIN	MAX	UNIT
			MIN	MAX			
f_{clock}	Clock frequency, CCK or RCK		0	80	0	80	MHz
t_w	Pulse duration	CCK or RCK high or low	6.3		6.3		ns
		$\overline{CCLR}$ low	8.4		8.4		
t_{su}	Setup time	$\overline{CCKEN}$ low before CCK↑	5.1		5.1		ns
		$\overline{CCLR}$ high before CCK↑	1.6		1.6		
		CCK↑ before RCK↑§	5.5		5.5		
t_h	Hold time	$\overline{CCKEN}$ low after CCK↑	0.6		0.6		ns

§ This setup time ensures that the register will see stable data from the counter outputs. The clocks may be tied together, in which case the register will be one clock pulse behind the counter.

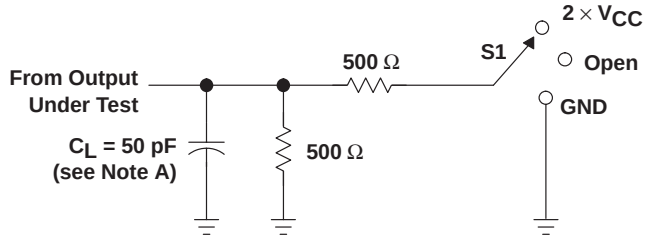
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
f_{max}	CCK or RCK		80			80		MHz
t_{PLH}	CCK	$\overline{RCO}$	4.5	8	11	4.5	13	ns
t_{PHL}			5.1	9	13.8	5.1	16.4	
t_{PLH}	$\overline{CCLR}$	$\overline{RCO}$	3.5	7	11	3.5	13.1	ns
t_{PLH}	RCK	Q	4.6	8	11.1	4.6	13	ns
t_{PHL}			3.9	7.6	11.8	3.9	13.9	
t_{PZH}	$\overline{OE}$	Q	4	8.3	13.2	4	15.6	ns
t_{PZL}			3.8	8.2	13.9	3.8	16.2	
t_{PHZ}	$\overline{OE}$	Q	5.3	8	10.3	5.3	11.5	ns
t_{PLZ}			6.1	9.1	11.5	6.1	13	
t_{PLH}	$\overline{CCKEN}$	$\overline{RCO}$	3.8	6.8	9.7	3.8	11.2	ns
t_{PHL}			2.8	7.6	11	2.8	12.8	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

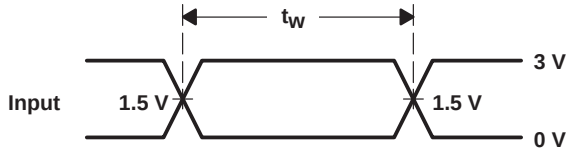
PARAMETER			TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	Outputs enabled	C_L = 50 pF,	f = 1 MHz	66	pF
		Outputs disabled			42	

PARAMETER MEASUREMENT INFORMATION

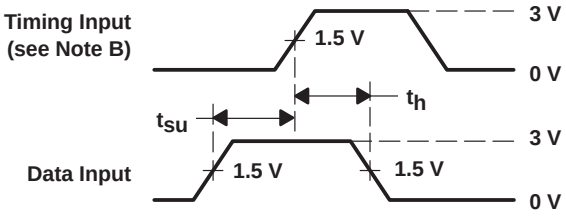


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND

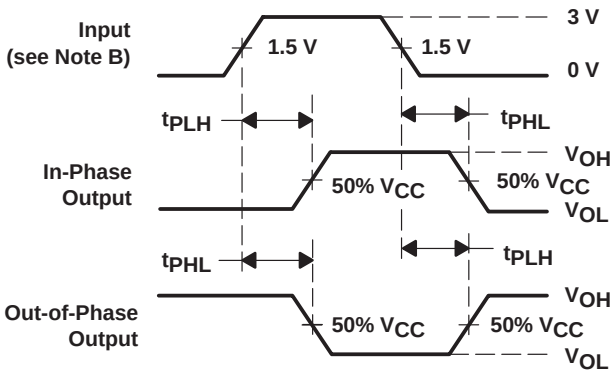
LOAD CIRCUIT



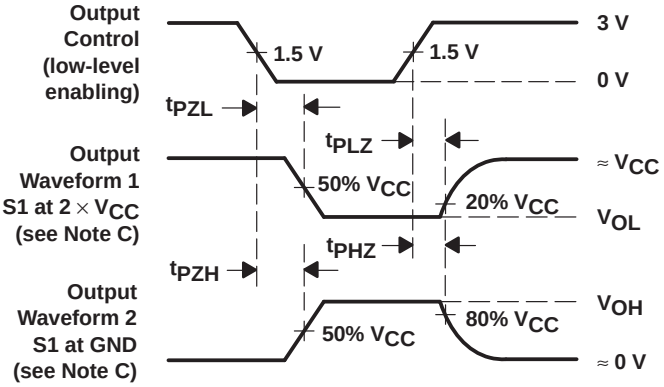
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

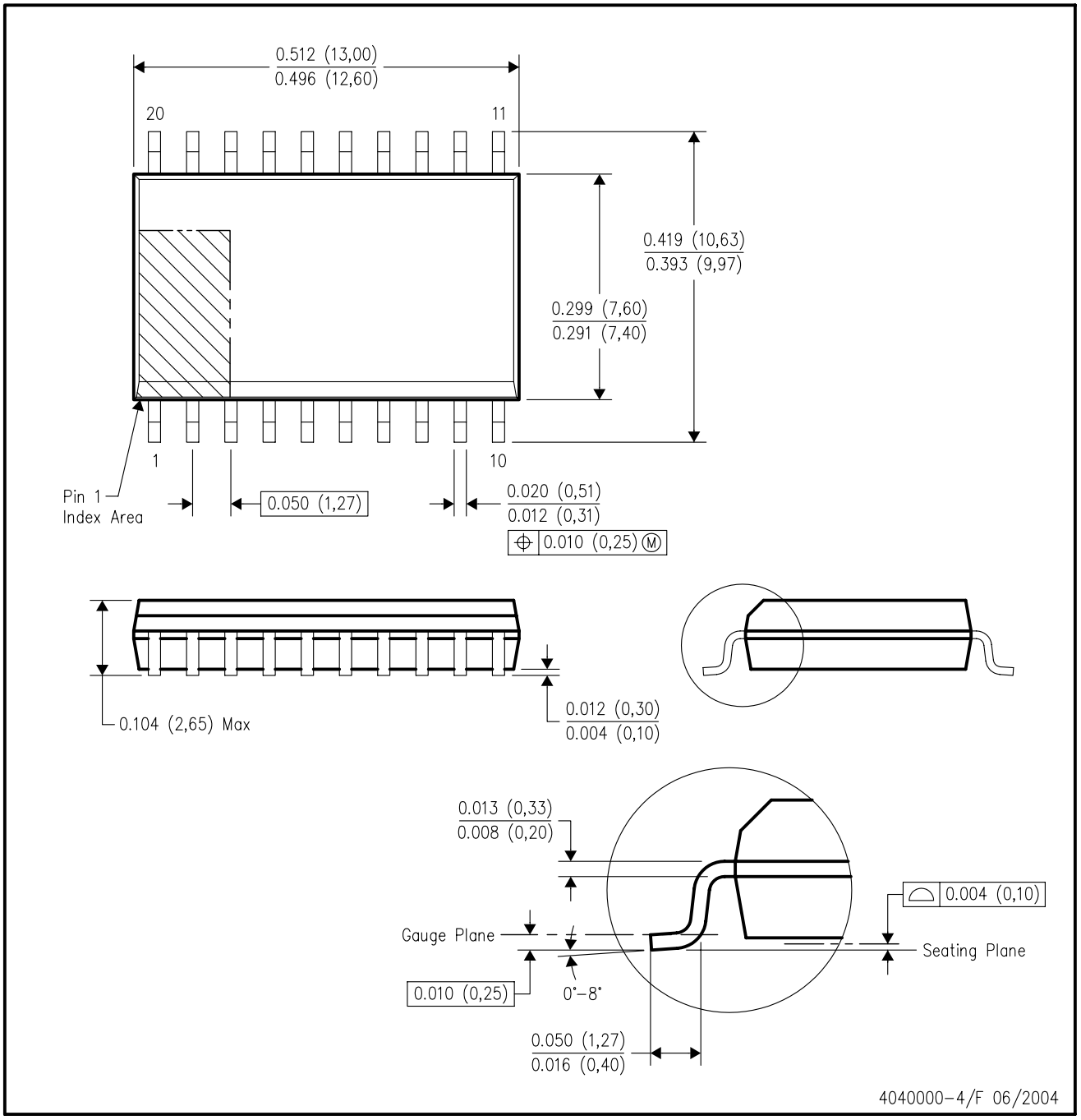
Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
74ACT11590DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI
74ACT11590DWR	OBSOLETE	SOIC	DW	0		TBD	Call TI	Call TI
74ACT11590N	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

DW (R–PDSO–G20) PLASTIC SMALL–OUTLINE PACKAGE

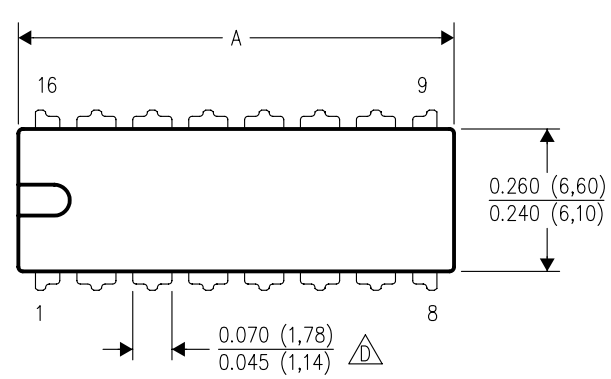


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AC.

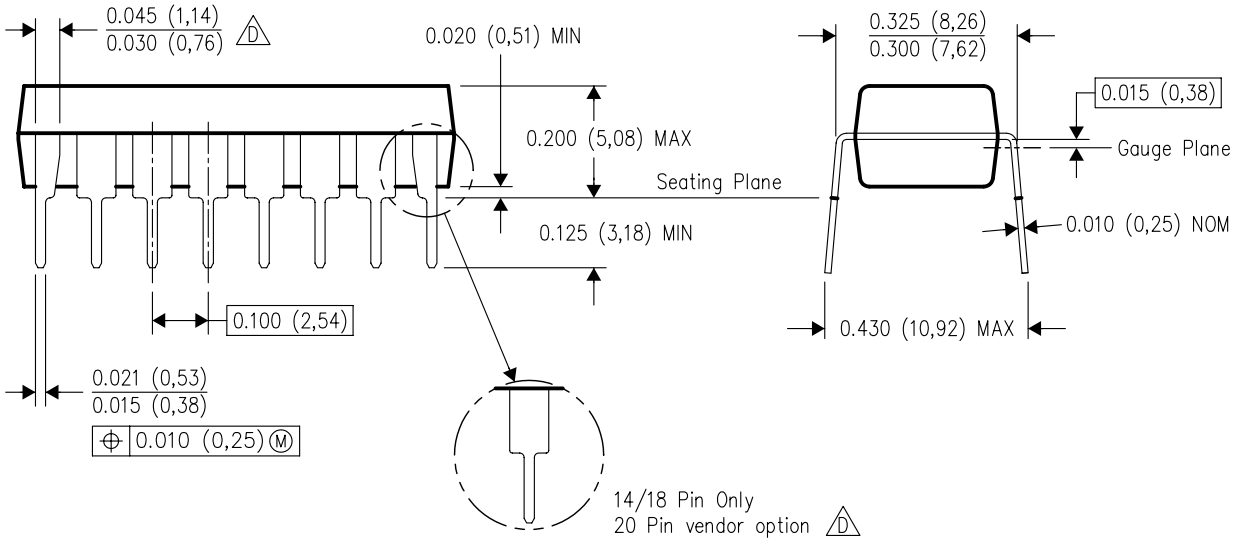
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

PACKAGING INFORMATION

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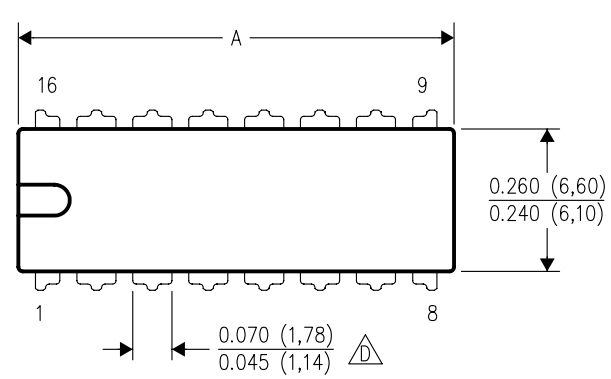
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



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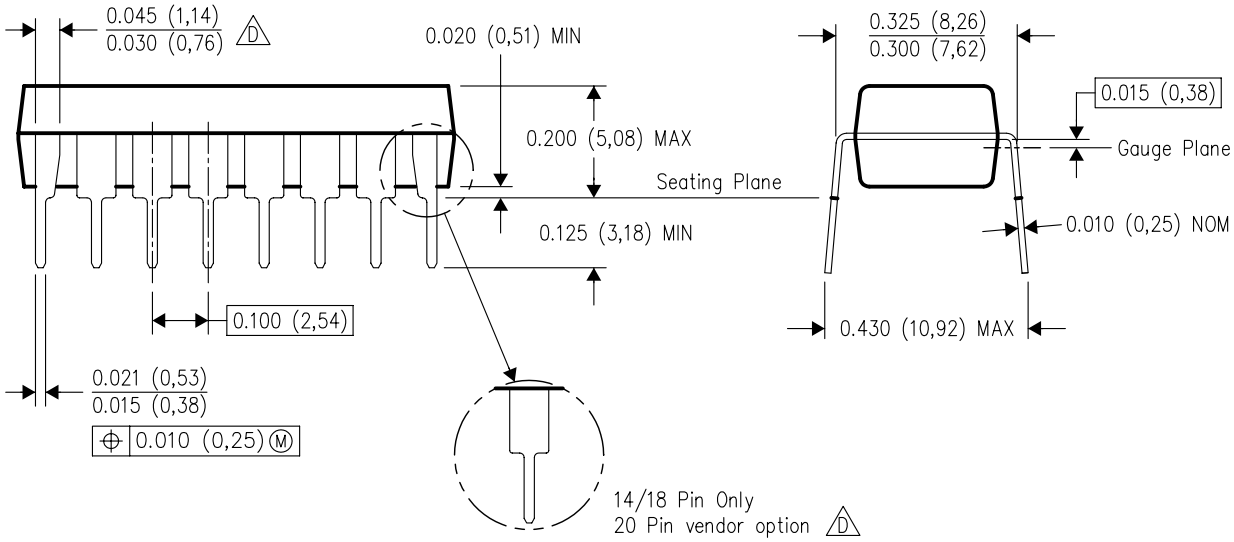
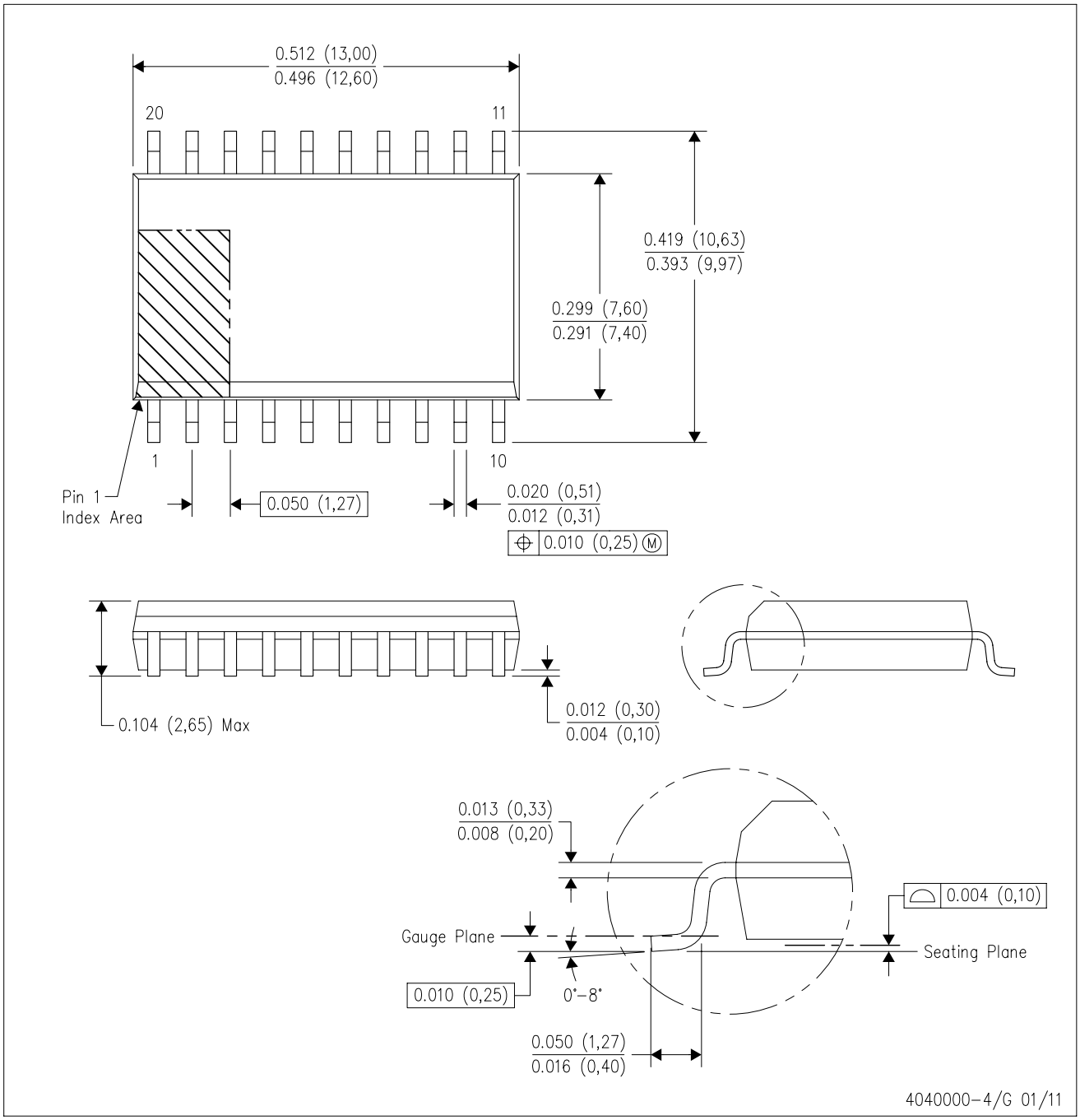
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R–PDSO–G20) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AC.

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